

TransFeed

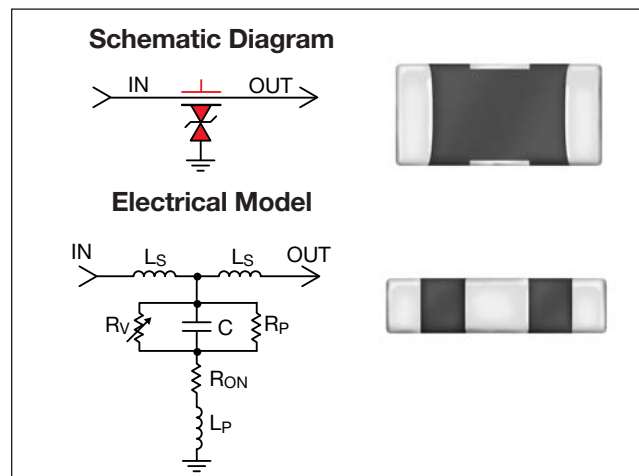
AVX Multilayer Ceramic Transient Voltage Suppressors TVS Protection and EMI Attenuation in a Single Chip



GENERAL DESCRIPTION

AVX has combined the best electrical characteristics of its TransGuard® Transient Voltage Suppressors (TVS) and its Feedthru Capacitors into a single chip for state-of-the-art overvoltage circuit protection and EMI reduction over a broad range of frequencies. This unique combination of multilayer ceramic construction in a feedthru configuration gives the circuit designer a single 0805 chip that responds to transient events faster than any TVS device on the market today, and provides significant EMI attenuation when in the off-state.

The reduction in parallel inductance, typical of the feedthru chip construction when compared to the construction of standard TVS or ceramic capacitor chips, gives the TransFeed product two very important electrical advantages: (1) faster “turn-on” time. Calculated response times of <200 pSec are not unusual with this device, and measured response times range from 200 – 250 pSec. The TransFeed “turn-on” characteristic is less than half that of an equivalent TransGuard® part — and TransGuards® clamp transient voltages faster than any other bipolar TVS solution such as diodes; (2) the second electrical advantage of lower parallel inductance, coupled with optimal series inductance, is the enhanced attenuation characteristics of the TransFeed product. Not only is there significantly greater attenuation at a higher self-resonance frequency, but the roll-off characteristic becomes much flatter, resulting in EMI filtering over a much broader frequency spectrum. Typical applications include filtering/protection on Microcontroller I/O Lines, Interface I/O Lines, Power Line Conditioning and Power Regulation.



TYPICAL APPLICATIONS

- Fingerprint ID Circuit
- Magnetic Field Circuit
- LCD Dashboard Driver

Where designers are concerned with both transient voltage protection and EMI attenuation, either due to the electrical performance of their circuits or due to required compliance to specific EMC regulations, the TransFeed product is an ideal choice.



HOW TO ORDER

V	2	F	1	05	A	150	Y	2	E	D	P
Varistor		Feedthru Capacitor		Voltage		Varistor Clamping Voltage		DC Resistance		Packaging Code	
				05 = 5.6VDC 09 = 9.0VDC 14 = 14.0VDC 18 = 18.0VDC		150 = 18V 200 = 22V 300 = 32V 400 = 42V 500 = 50V		1 = 0.150 Ohms 2 = 0.200 Ohms 3 = 0.250 Ohms		D = 1,000 R = 4,000 T = 10,000	
Chip Size			No. of Elements		Energy Rating		Capacitance Tolerance		Feedthru Current		Termination Finish
2 = 0805 3 = 0612					X = 0.05J A = 0.1J C = 0.3J		Y = +100/-50%		D = 500 mA E = 750 mA F = 1.0 Amp		P = Ni/Sn Alloy (Plated)

TRANSFEED ELECTRICAL SPECIFICATIONS

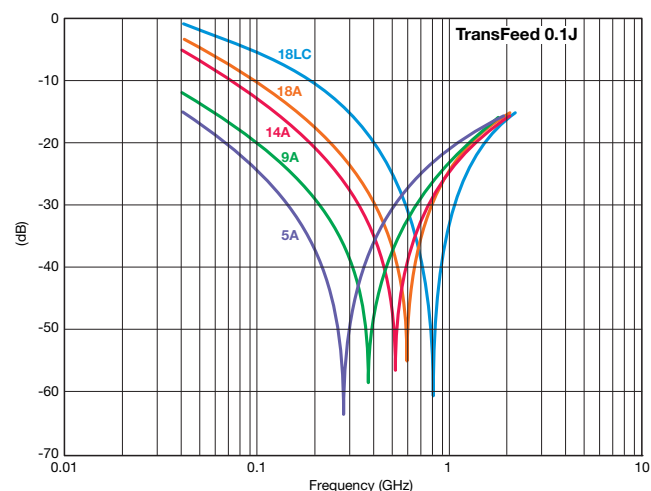
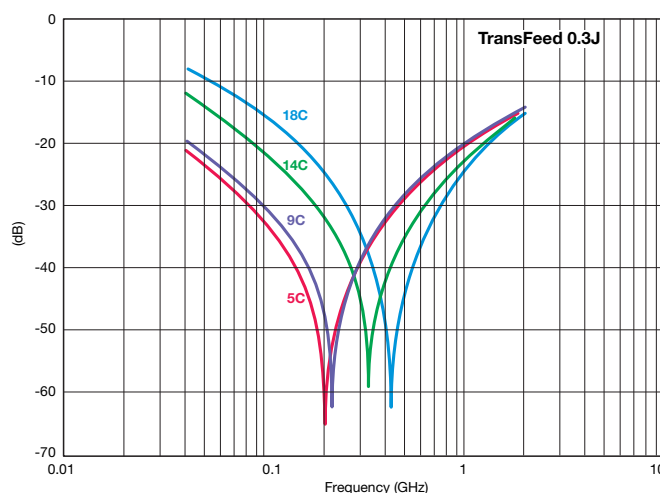
AVX Part Number	Working Voltage (DC)	Working Voltage (AC)	Breakdown Voltage	Clamping Voltage	Maximum Leakage Current	Transient Energy Rating	Peak Current Rating	Typical Cap	DC Resistance	Maximum Feedthru Current
V2F105A150Y2E__	5.6	4.0	8.5±20%	18	35	0.10	30	800	0.200	0.75
V2F105C150Y1F__	5.6	4.0	8.5±20%	18	35	0.30	120	2500	0.150	1.00
V2F109A200Y2E__	9.0	6.4	12.7±15%	22	25	0.10	30	575	0.200	0.75
V2F109C200Y1F__	9.0	6.4	12.7±15%	22	25	0.30	120	1800	0.150	1.00
V2F114A300Y2E__	14.0	10.0	18.5±12%	32	15	0.10	30	300	0.200	0.75
V2F114C300Y1F__	14.0	10.0	18.5±12%	32	15	0.30	120	900	0.150	1.00
V2F118A400Y2E__	18.0	13.0	25.5±10%	42	10	0.10	30	200	0.200	0.75
V2F118C400Y1F__	18.0	13.0	25.5±10%	42	10	0.30	120	500	0.150	1.00
V2F118X500Y3D__	18.0	13.0	25.5±10%	50	10	0.05	20	75	0.250	0.50
V3F418A400Y3G__	18.0	13.0	25.5±10%	42	10	0.10	20	150	0.200	0.30
V3F418X500Y3G__	18.0	13.0	25.5±10%	50	10	0.05	15	65	0.250	0.20

Termination Finish Code

Packaging Code

- V_W (DC) DC Working Voltage (V)
 V_W (AC) AC Working Voltage (V)
 V_B Typical Breakdown Voltage (V @ 1mA_{DC})
 V_B Tol V_B Tolerance is ± from Typical Value
 V_C Clamping Voltage (V @ 1A 8x20μS)
 I_L Maximum Leakage Current at the Working Voltage (μA)
 E_T Transient Energy Rating (J, 10x1000μS)
 I_P Peak Current Rating (A, 8x20μS)
Cap Typical Capacitance (pF) @ 1MHz and 0.5 V
DCR DC Resistance (Ohms)
 I_{FT} Maximum Feedthru Current (A)

dB Attenuation vs Frequency



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AVX Multilayer Ceramic Transient Voltage Suppressors

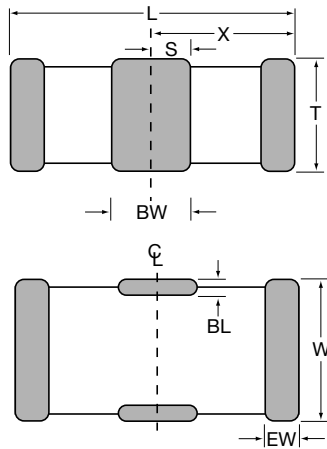
TVS Protection and EMI Attenuation in a Single Chip



DIMENSIONS

	L	W	T	BW	BL	EW	X	S
0805	2.01 ± 0.20 (0.079 ± 0.008)	1.25 ± 0.20 (0.049 ± 0.008)	1.143 Max. (0.045 Max.)	0.46 ± 0.10 (0.018 ± 0.004)	0.18 + 0.25 - 0.08 (0.007 + 0.010 - 0.003)	0.25 ± 0.13 (0.010 ± 0.005)	1.02 ± 0.10 (0.040 ± 0.004)	0.23 ± 0.05 (0.009 ± 0.002)

mm (inches)

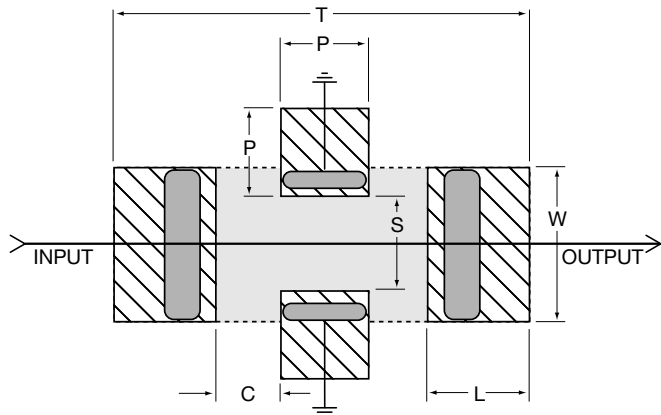


RECOMMENDED SOLDER PAD LAYOUT (Typical Dimensions)

	T	P	S	W	L	C
0805	3.45 (0.136)	0.51 (0.020)	0.76 (0.030)	1.27 (0.050)	1.02 (0.040)	0.46 (0.018)

mm (inches)

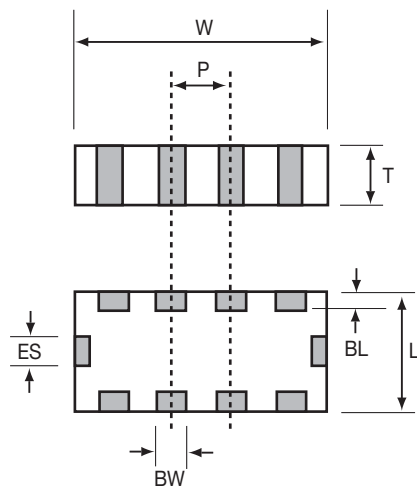
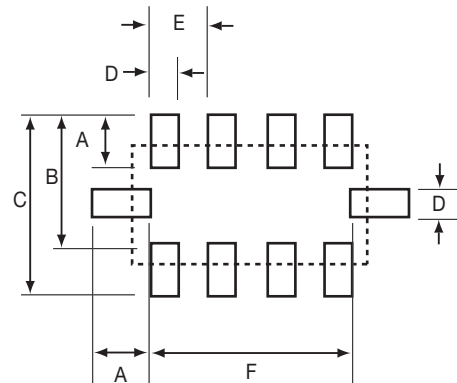
4 Pad Layout



TransFeed Array - V3F4 Series



TVS Protection and EMI Attenuation in a 4-Element Array



V3F4

DIMENSIONS

mm (inches)

L	W	T	BW	BL	ES	P
1.60 ± 0.20 (0.063 ± 0.008)	3.25 ± 0.15 (0.128 ± 0.006)	1.22 Max. (0.048 Max.)	0.41 ± 0.10 (0.016 ± 0.004)	0.18 +0.25 -0.08 (0.007 +0.010 -0.003)	0.41 ± 0.10 (0.016 ± 0.004)	0.76 REF (0.030 REF)

mm (inches)

A	B	C	D	E	F
0.60 (0.024)	1.60 (0.064)	2.20 (0.088)	0.35 (0.014)	0.76 (0.030)	2.60 (0.104)

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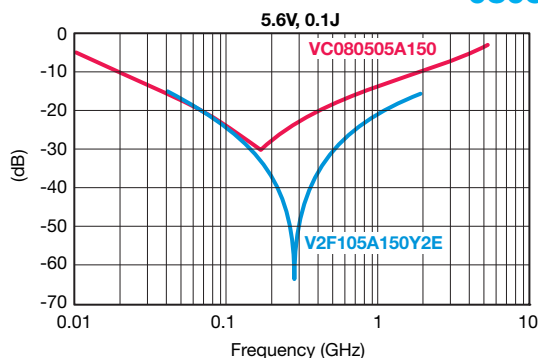
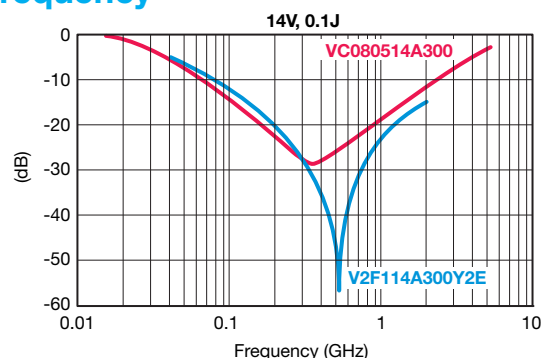
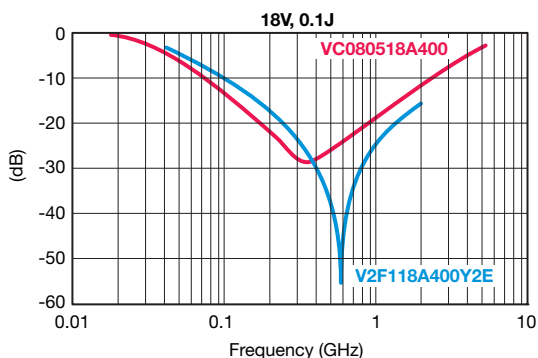
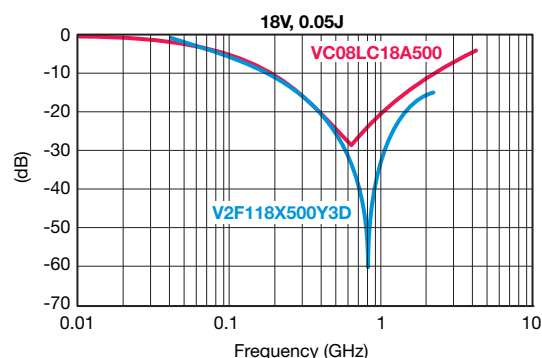
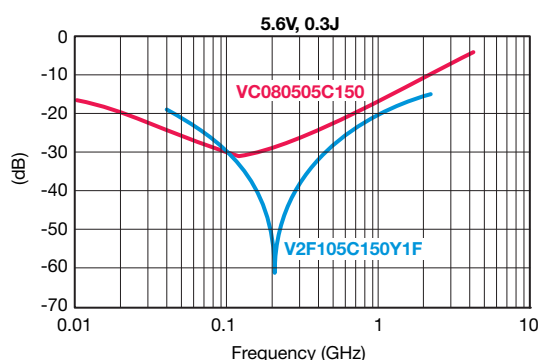
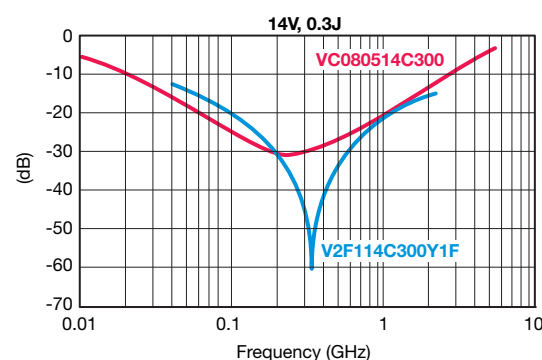
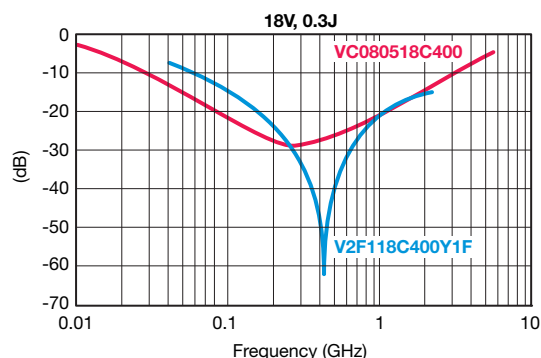
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PERFORMANCE CHARACTERISTICS

INSERTION LOSS COMPARISON (TransFeed vs TransGuard®)

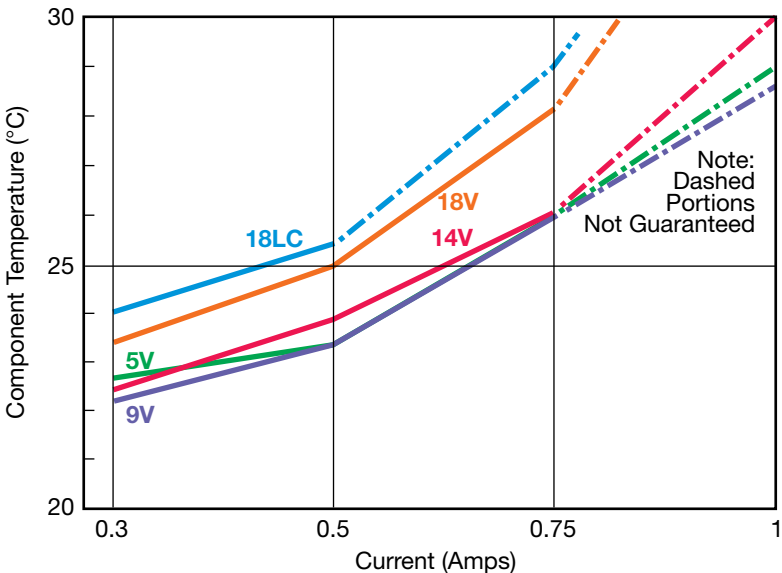
0805 – dB vs Frequency



PERFORMANCE CHARACTERISTICS

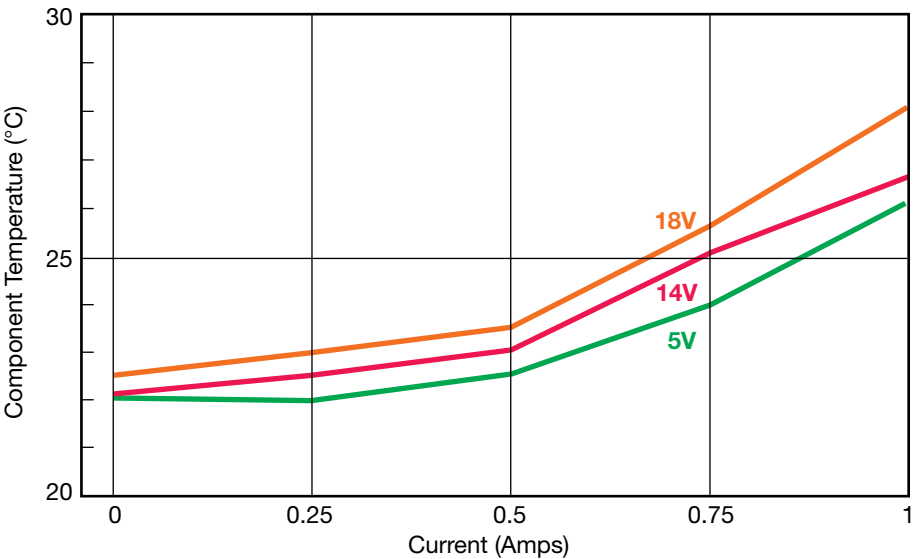
CURRENT vs TEMPERATURE

0805 – 0.1 Joule



CURRENT vs TEMPERATURE

0805 – 0.3 Joule



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PERFORMANCE CHARACTERISTICS

FEEDTHRU VARISTORS

AVX Multilayer Feedthru Varistors (MLVF) are an ideal choice for system designers with transient strike and broadband EMI/RFI concerns.

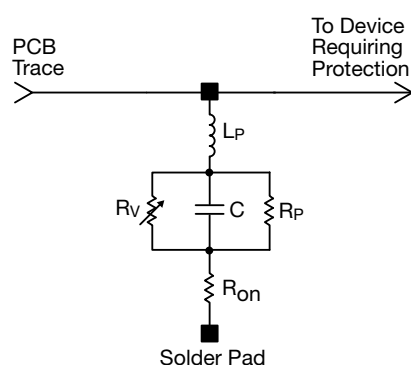
Feedthru Varistors utilize a ZnO varistor material and the electrode pattern of a feedthru capacitor. This combination allows the package advantage of the feedthru and material advantages of the ZnO dielectric to be optimized.

ZnO MLV Feedthrus exhibit electrical and physical advantages over standard ZnO MLVs. Among them are:

1. Faster Turn on Time
2. Broadband EMI attenuation
3. Small size (relative to discrete MLV and EMI filter schemes)

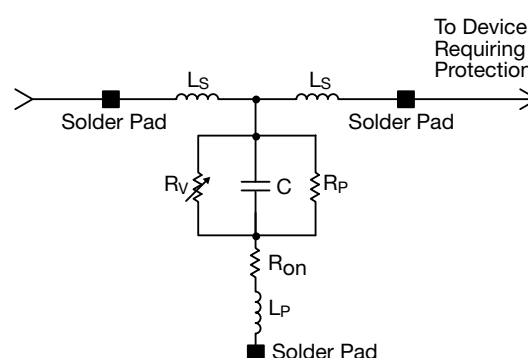
The electrical model for a ZnO MLV and a ZnO Feedthru MLV are shown below. The key difference in the model for the Feedthru is a transformation in parallel to series inductance. The added series inductance helps lower the injected transient peak current (by $2\pi fL$) resulting in an additional benefit of a lower clamping voltage. The lowered parallel inductance decreases the turn on time for the varistor to <250ps.

Discrete MLV Model



Where: R_V = Voltage Variable resistance (per VI curve)
 $R_P \geq 10^{12} \Omega$
 C = defined by voltage rating and energy level
 R_{on} = turn on resistance
 L_P = parallel body inductance

Discrete MLVF Model



Where: R_V = Voltage Variable resistance (per VI curve)
 R_P = Body IR
 C = defined by voltage rating and energy level
 R_{on} = turn on resistance
 L_P = minimized parallel body inductance
 L_S = series body inductance

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AVX Multilayer Ceramic Transient Voltage Suppressors TVS Protection and EMI Attenuation in a Single Chip



PERFORMANCE CHARACTERISTICS

APPLICATIONS

- EMI Suppression
- Broadband I/O Filtering
- Vcc Line Conditioning

FEATURES

- Small Size
- Low ESR
- Ultra-fast Response Time
- Broad S21 Characteristics

MARKET SEGMENTS

- Computers
- Automotive
- Power Supplies
- Multimedia Add-On Cards
- Bar Code Scanners
- Remote Terminals
- Medical Instrumentation
- Test Equipment
- Transceivers
- Cellular Phones / Pagers

TYPICAL CIRCUITS REQUIRING TRANSIENT VOLTAGE PROTECTION AND EMI FILTERING

The following applications and schematic diagrams show where TransFeed TVS/ EMI filtering devices might be used:

- System Board Level Interfaces: (Fig. 1)
Digital to RF
Analog to Digital
Digital to Analog
- Voltage Regulation (Fig. 2)
- Power Conversion Circuits (Fig. 3)
- GaAs FET Protection (Fig. 4)

Fig. 1 – System Interface

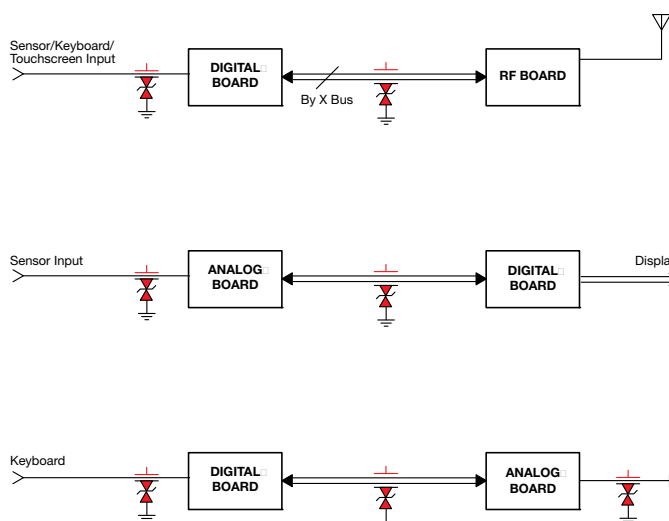


Fig. 2 – Voltage Regulators

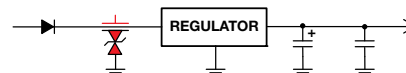


Fig. 3 – Power Conversion Circuits/Power Switching Circuits

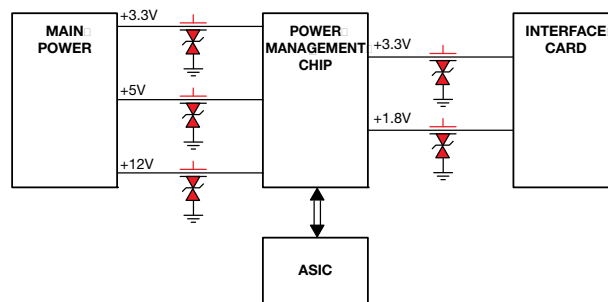
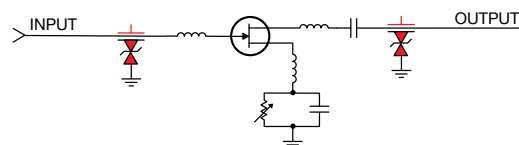


Fig. 4 – GaAs FET Protection



SPECIFICATION COMPARISON

MLVF 0805	PARAMETER	MLV 0805
5ph	L_s typical	N/A
<600nh	L_p typical	<1.5nh
<0.025 Ω	R_{on} typical	<0.1 Ω
100pf to 2.5nf	C typical	100pf to 5.5nf
see VI curves	R_v typical	see VI curves
>0.25 x 10 ¹² Ω	R_p typical	>1 x 10 ¹² Ω
<250ps	Typical turn on time Typical frequency response	<500ps

A comparison table showing typical element parameters and resulting performance features for MLV and MLVF is shown above.